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PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10087989	FILING DATE 03/05/2002	CLASS 438	SUBCLASS 438	GAU 2812	EXAMINER VV
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\*\*APPLICANTS: Han Hongtao; Mathews Jay;

\*\*CONTINUING DATA VERIFIED: Yes DV  
THIS APPLICATION IS A CIP OF 09/983,278 10/23/2001  
WHICH CLAIMS BENEFIT OF 60/273,321 03/06/2001

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\*\* FOREIGN APPLICATIONS VERIFIED: None DV

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no	ATTORNEY DOCKET NO
35 USC 119 conditions met	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no	DOC.072CIP
Verified and Acknowledged Examiner's initials		
TITLE : Thick wafer processing and resultant products		
U.S.DEP'T. OF COMM/PAT & TM-PTO-436L (Rev. 12-94)		

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
		DRAWING	
Amount Due		Sheets Drawg.	Fig.s Drawg.
Date Paid		Print Fig.	
TERMINAL		Primary Examiner	
DISCLAIMER		PREPARED FOR ISSUE	
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